

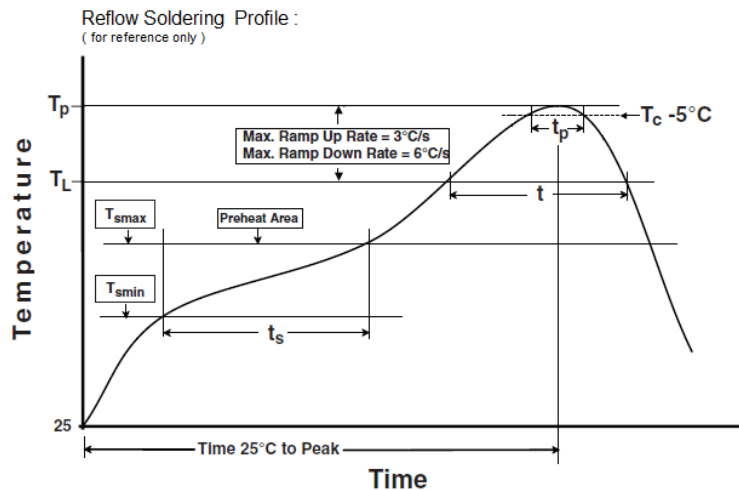
Soldering Method

• Reflow Profile

FASTRON component is resistant to soldering heat condition $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 10 ± 1 second.

The optimal reflow profile for a circuit board assembly is dependent on the solder material, solder amount, flux, and temperature limit of each soldered component, heat transfer characteristic of the circuit board and the layout of all the components. As such, there is not specific soldering profile for specific part.

General reflow soldering profile for reference as the following:



Lead (Pb)-Free Solder Reflow Profiles	
Profile Feature	Pb-free Assembly
Temperature min (T_{smin})	150 °C
Temperature max (T_{smax})	200 °C
Preheat Dwell Time (t_s)	60 to 120 seconds
Average ramp-up rate (T_{smax} to T_p)	3 °C / second max.
Liquidous temperature (T_L)	217 °C
Time at liquidous (t)	60 to 150 seconds
Peak package body temperature (T_p)	255 ± 5 °C
Time (t_p) within 5 °C of the specified temperature (T_c)	30 seconds
Average ramp-down rate (T_p to T_{smax})	6 °C / second max.
Time 25 °C to peak temperature	8 minutes max.